EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	2	"20040022029"	US-PGPUB; USPAT	OR	OFF	2008/07/04 19:39
L3	15	("5395679" | "5621243" | "5892279" | "5920119" | "5928768" | "6033787" | "6054762" | "6055154" | "6060772" | "6201696" | "6261703" | "6309737" | "6310775" | "6483185" | "6563709").PN. OR ("7019975").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/04 19:39
L4	0	"2000240580" or "2001194034"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/04 19:40
L5	3	"2000240580" or "2001194034"	JPO	OR	OFF	2008/07/04 19:40
L6	24	("4770953" | "5011732" | "5130498" | "5145540" | "5213877" | "5529852" | "5616421" | "5675474").PN. OR ("6033787").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/04 20:38
L7	21	("3927815" | "4672739" | "4781970" | "4979015").PN. OR ("5213877").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/04 20:55
L8	7105	428/209	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 21:05

L9	2429	428/210	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 21:07
L10	6663	361/704	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 21:22
L11	878498	(semiconductor or die or dice or chip or IC)	USPAT	OR	ON	2008/07/04 21:32
L12	36958	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) with alloy	USPAT	OR	ON	2008/07/04 21:32
L13	2	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) near alloy with ("Y" or "Sc" or "La" or "Ce" or "Nd" or "Sm" or "Gd" or "Tb" or "Dy" or "Er" or "Th" or "Sr") and ("Al" or aluminum) near ("Si" or silicon$1) with (attach$3 or solder$3 or braz$3)	USPAT	OR	ON	2008/07/04 21:33
L14	849	228/121	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 21:44
L15	786	257/703	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 21:59
L16	3645	257/706	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 22:07

L17	2333	257/750	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 22:10
L18	19	257/E23.009	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 22:41
S1	1	"3893224".pn.	USPAT	OR	OFF	2008/07/03 21:31
S2	1	"6426154".pn.	USPAT	OR	OFF	2008/07/03 21:38
S3	1	"20070160858"	US-PGPUB; USPAT	OR	OFF	2008/07/03 21:58
S4	9	257/E23.188	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/03 21:59
S5	3484	257/712	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/03 22:00
S6	4307	428/469	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/03 22:04
S7	4167	428/698	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/03 22:17

S8	0	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) near (plate or layer) with clad same ("Al" or aluminum) near alloy with (pad) and ("Al" or aluminum) near ("Si" or silicon$1) with (attach$3 or solder$3 or braz$3)	USPAT	OR	ON	2008/07/03 22:22
S9	0	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) near (plate or layer) with clad and ("Al" or aluminum) near alloy with (pad) and ("Al" or aluminum) near ("Si" or silicon$1) with (attach$3 or solder$3 or braz$3)	USPAT	OR	ON	2008/07/03 22:23
S10	1	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) near (plate or layer) and ("Al" or aluminum) near alloy with (pad) and ("Al" or aluminum) near ("Si" or silicon$1) with (attach$3 or solder$3 or braz$3)	USPAT	OR	ON	2008/07/03 22:24
S11	1	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) with (plate or layer) and ("Al" or aluminum) near alloy with (pad) and ("Al" or aluminum) near ("Si" or silicon$1) with (attach$3 or solder$3 or braz$3)	USPAT	OR	ON	2008/07/03 22:24

| S12 | 76 | (semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) with (plate or layer) and ("Al" or aluminum) near alloy and ("Al" or aluminum) near ("Si" or silicon$1) with (attach$3 or solder$3 or braz$3) | USPAT | OR | ON | 2008/07/03 22:25 |

7/4/08 10:42:57 PM
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